



985M Soldering Flux

Low-Solids, No-Clean Flux

Product Description

Kester 985M Soldering Flux is a low-solids, halide-free, no-clean flux that is designed for wave solder and touch up processes. 985M was developed for use with both traditional tin-lead and lead-free solder alloys. 985M exhibits improved soldering performance to minimize solder bridges (shorts) during all soldering operations.

Performance Characteristics:

- Improves soldering performance
- Eliminates the need and expense of cleaning
- Non-corrosive tack-free residues
- Compliant to GR-78-CORE (Telcorida/Bellcore)
- Classified as ORL0 under IPC J-STD-004 and ORM0 under IPC J-STD-004B

RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive. Additional RoHS information is located at https://www.kester.com/downloads/environmental.

Physical Properties

Specific Gravity @ 25 °C (typical): 0.805

Acid Number (Typical): 20.0 mg KOH/g of flux

Percent Solids (Theoretical): 3.6%

Reliability Properties

Copper Mirror: No Breakthrough "L"

Tested to J-STD-004B, IPC-TM-650, Method 2.3.32

Corrosion Test:

No Corrosion "L"

Tested to J-STD-004, IPC-TM-650, Method 2.6.15B





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Minor Corrosion "M"

Tested to J-STD-004B, IPC-TM-650, Method 2.6.15C

Bono Corrosion Test: Pass, Fc=0.7%

Test Conditions: 85 °C, 85% RH, 15 days, 12V

Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Chloride & Bromide: None Detected

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

Electrochemical Migration (ECM): Pass

Tested to J-STD-004B, IPC-TM-650, Method 2.6.14.1 Tested Conditions: 65 °C, 85% RH, 500hrs, 100V

Surface Insulation Resistance (SIR), Bellcore, IPC: Pass

GR-78 13.1.3

Tested Conditions: 35 °C, 85% RH, 4 Days, 100V

Surface Insulation Resistance (SIR): Pass

Tested to J-STD-004B, IPC-TM-650, Method 2.6.3.7 Tested Conditions: 40 °C, 90% RH, 7 Days, 12.5V

Surface Insulation Resistance (SIR): Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3 Tested Conditions: 85 °C, 85% RH, 7 Days, 100V

Flux Application

985M is specially designed for spray and wave applications. It is not designed to be used in a foam application. The flux deposition target should start at 90 to 190 μ g of solids/cm² (600 to 1200 μ g of solids/in²).







Process Considerations

The optimum preheat temperature for most circuit assemblies is 85 to 105 °C (185 to 221 °F) as measured on the top or component side of the assembly. It is important to note that the optimum preheat temperature for a given assembly will depend on the combination of machine design, circuit board design (board mass or size and component mix), board thickness, length of contact time with molten solder, solder wave shape, speed of solder flow, preheating time and alloy used in the solder pot. The key is to preheat the board to start the activation of the flux yet not burn it up prior to reaching the solder pot. For 985M, the maximum preheat temperature on the bottom side of the board is 130 °C.

Leaded solders (Sn63Pb37) will require a dwell time of 2 to 4 seconds. Lead-free solders (Sn96.5Ag3.0Cu0.5) will require a dwell time in the wave of 4 to 7 seconds. Any time greater than 7 seconds, copper dissolution for OSP, ImAg, and ImSn boards may occur.

The above information is a guideline and it is advisable to note that the optimum settings for a given assembly may vary and this is dependent on the circuit board design, board thickness, components used and equipment used. A design of experiment is recommended to be done to optimize the soldering process. If you have any questions, please contact Kester Technical Support.

Touch-Up Application

Flux pens should only be used as a last resort. Any flux applied to the solder location should be kept to the location of the solder connection being soldered.

Flux Control

Kester PS-22 Test Kit and procedure are available to insure the level of solids in the flux. The instructions of how to use this kit will come with the purchase of the kit. This could be used as a means of incoming inspection.

Cleaning

985M residues are non-conducive and do not require removal in most applications. If residue removal is required it can be removed using commercially available flux residue cleaner. Contact Kester Technical Support for additional assistance.

Additional Information

Additional product information is available in 985M Data Package. Contact your Kester representative for a copy.





TECHNICAL DATA SHEET

Storage, Handling and Shelf Life

985M is flammable. Store away from sources of ignition. Shelf life is 1 year from the date of manufacture when handled properly and held at 10 to 25 °C (50 to 77 °F).

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product. Safety Data Sheets are available at https://www.kester.com/downloads/sds.

Contact Information

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